

containing a hydroxystyrene group, wherein at least a part of the hydroxy groups of the hydroxystyrene groups of the repeating units are protected by said acid-decomposing group of formula (I).

4 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the compound (b-1) is a compound generating a sulfonic acid by the irradiation of an active light or radiation and the compound (b-2) is a compound generating a carboxylic acid by the irradiation of an active light or radiation.

5 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the composition further contains an organic basic compound.

8 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the resin (a) is from 10 to 99.9% by weight based on the total weight excluding a solvent of the composition.

9 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the resin (a) is from 50 to 99.5% by weight based on the total weight excluding a solvent of the composition.

10 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the resin (a) is from 70 to 99.0% by weight based on the total weight of the composition excluding the solvent.

64
11 (Twice Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the composition further contains an alkali-soluble resin which does not contain an acid-decomposing group.

65
12 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the component (b-1) is from 0.001 to 40% by weight based on the total weight of the composition excluding the solvent.

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13 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the component (b-1) is from 0.01 to 20% by weight based on the total weight of the composition excluding the solvent.

14 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the component (b-1) is from 0.1 to 5% by weight based on the total weight of the composition excluding the solvent.

15 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the component (b-2) is from 0.1 to 20% by weight based on the total weight of the composition excluding the solvent.

16 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the component (b-2) is from 0.5 to 10% by weight based on the total weight of the composition excluding the solvent.

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17 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the amount of the component (b-2) is from 1 to 7% by weight based on the total weight of the composition excluding the solvent.

18 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the weight ratio of the components (b-2)/(b-1) is from 0.01 to 5.

19 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the weight ratio of the components (b-2)/(b-1) is from 0.05 to 3.

20 (Amended). The positive-working radiation-sensitive composition according to claim 21, wherein the weight ratio of the components (b-2)/(b-1) is from 0.1 to 2.

21 (Amended). A positive-working radiation-sensitive composition comprising

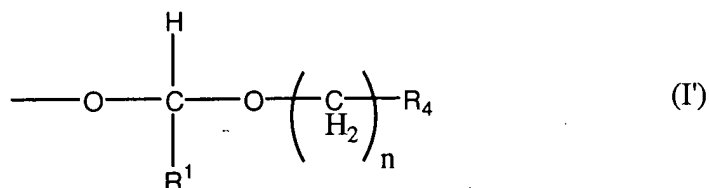
(a) a resin having an acid-decomposing group represented by the following formula (I'), which is decomposed by the action of an acid to increase the solubility in an alkali developer,

(b-1) at least one compound which generates an acid by the irradiation of an active light or radiation and contributes to the decomposition reaction of the above-described acid-decomposing group,

(b-2) at least one compound which generates an acid by the irradiation of an active light or radiation but does not contribute to the decomposition reaction of the above-described acid-decomposing group,

(c) a surface active agent, and

(d) a solvent,



wherein R₁ represents an alkyl group having from 1 to 4 carbon atoms, R₄ represents a substituted or unsubstituted aryl group or a substituted or unsubstituted cyclic alkyl group having from 3 to 15 carbon atoms; n represents a natural number of from 1 to 4.